

PRELIMINARY AMENDMENT

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Title: TEST UNIT AND ENCLOSURE FOR TESTING INTEGRATED CIRCUITS

Assignee: Intel Corporation

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Claims

Please amend the claims as follows:

Claims 1-16 (Canceled)

17. (Original) An enclosure comprising:

a hollow substantially cylindrical insulating core having a first orifice having a first diameter and at least one further orifice, the first orifice constructed and arranged for coupling the interior of the insulating core to a temperature controlled air source and a second orifice constructed and arranged for allowing air entering the core through the first orifice to pass over a test fixture substantially enclosed within the core prior to exiting through the further orifice, the hollow substantially cylindrical insulating core being partially coated with a conductive material maintained at a reference potential relative to the test fixture.

18. (Original) The enclosure of claim 17, wherein the hollow substantially cylindrical insulating core comprises fiberglass.

19. (Original) The enclosure of claim 17, wherein the first diameter is about 4.5 inches.

20. (Original) The enclosure of claim 17, wherein the conductive material comprises a semiconductor.

21. (Original) The enclosure of claim 17, wherein the conductive material comprises a metal.

22. (Original) The enclosure of claim 21, wherein the metal comprises copper.

23. (Original) The enclosure of claim 17, wherein the enclosure has at least two uncoated chamfered edges.

24. (Original) A method of fabricating an enclosure, the method comprising:

forming a cylindrically shaped block of insulating material having a substantially flat first end, a substantially flat second end, and an outer surface;

forming a first hole having a first diameter in the cylindrically shaped block to form a first inner surface;

forming a second hole having a second diameter in the cylindrically shaped block to form a second inner surface, the second diameter being greater than the first diameter; and

coating the outer surface, the substantially flat first end, the first inner surface, and the second inner surface with a conductive material.

25. (Original) The method of claim 24, wherein coating the outer surface, the first end, the first inner surface, and the second inner surface with a conductive material comprises:

coating the outer surface, the first end, the first inner surface and the second inner surface with aluminum.

26. (Original) The method of claim 25, wherein coating the outer surface, the first end, the first inner surface and the second inner surface with aluminum comprises:

depositing the aluminum on the outer surface, the first end, the first inner surface and the second inner surface by chemical vapor deposition.

27. (Original) The method of claim 24, wherein coating the outer surface, the first end, the first inner surface, and the second inner surface with a conductive material comprises:

coating the outer surface, the first end, the first inner surface and the second inner surface with a semiconductor.

28. (Original) The method of claim 27, wherein coating the outer surface, the first end, the first inner surface and the second inner surface with a semiconductor comprises:

painting the semiconductor on the outer surface, the first end, the first inner surface and the second inner surface.

29. (Original) The method of claim 27, wherein coating the outer surface, the first end, the first inner surface and the second inner surface with a semiconductor comprises:

spraying the semiconductor on the outer surface, the first end, the first inner surface and the second inner surface.